

**Notice of References Cited**

Application/Control No.

09/976,067

Applicant(s)/Patent Under  
Reexamination  
PENG ET AL.

Examiner

Kripa Sagar

Art Unit

1756

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	""Innovations in defluxing Engineered chemistries for removing flux residue on back end solder reflowed bumped wafers" ; M.Bixenman, Semicon West (2002) pp. 67-72
	V	
	W	
	X	

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